

Fast Rectifiers (Glass Passivated)

EGF1A, EGF1B, EGF1C, EGF1D

Features

- Low Forward Voltage Drop
- Low Profile Package
- Fast Switching for High Efficiency
- These Devices are Pb-Free, Halide Free and are RoHS Compliant

ABSOLUTE MAXIMUM RATINGS (T_A = 25°C unless otherwise noted)

			Va	lue		
Symbol	Parameter	1A	1B	1C	1D	Unit
V_{RRM}	Maximum Repetitive Reverse Voltage	50	100	150	200	V
I _{F(AV)}	Average Rectified Forward Current, @ $T_L = 100^{\circ}C$		1.	.0		Α
I _{FSM}	Non-repetitive Peak Forward Surge Current 8.3 ms Single Half-Sine-Wave		3	0		Α
T _{stg}	Storage Temperature Range	-	-65 tc	+175	5	°C
TJ	Operating Junction Temperature	-	-65 tc	+175	5	°C

Stresses exceeding those listed in the Maximum Ratings table may damage the device. If any of these limits are exceeded, device functionality should not be assumed, damage may occur and reliability may be affected.

THERMAL CHARACTERISTICS

Symbol	Parameter	Value	Unit
V_{RRM}	Maximum Repetitive Reverse Voltage	200	V
P_{D}	Power Dissipation	2.0	W
$R_{\theta JA}$	Thermal Resistance, Junction to Ambient*	85	°C/W
$R_{\theta JL}$	Thermal Resistance, Junction to Lead*	30	°C/W

^{*}Device mounted on FR-4 PCB 0.013 mm.

ELECTRICAL CHARACTERISTICS (T_A = 25°C unless otherwise noted)

			Dev	ice		
Symbol	Parameter	1A	1B	1C	1D	Unit
V _F	Forward Voltage @ 1.0 A		1	.0		V
t _{rr}	Reverse Recovery Time $I_F = 0.5 \text{ A}, I_R = 1.0 \text{ A}, I_{RR} = 0.25 \text{ A}$		5	0		ns
I _R	Reverse Current @ Rated V_R $T_A = 25$ °C $T_A = 100$ °C		1 1(-		μ Α μ Α
C _T	Total Capacitance $V_R = 4.0 \text{ V}, f = 1.0 \text{ MHz}$		1	5		pF

Product parametric performance is indicated in the Electrical Characteristics for the listed test conditions, unless otherwise noted. Product performance may not be indicated by the Electrical Characteristics if operated under different conditions.



COLOR BAND DENOTES CATHODE

SMA (DO-214AC)

CASE 403AE

MARKING DIAGRAM



\$Y = Logo

&Z = Assembly Plant Code

&3 = 3–Digit Date Code

EGF1x = Specific Device Code (x = A, B, C, D)

ORDERING INFORMATION

Device	Package	Shipping [†]
EGF1A	SMA	7500 / Tape &
EGF1B	(Pb-Free, Halide Free)	Reel
EGF1C	rialide riee)	
EGF1D		

[†]For information on tape and reel specifications, including part orientation and tape sizes, please refer to our Tape and Reel Packaging Specifications Brochure, BRD8011/D.

EGF1A, EGF1B, EGF1C, EGF1D

TYPICAL CHARACTERISTICS

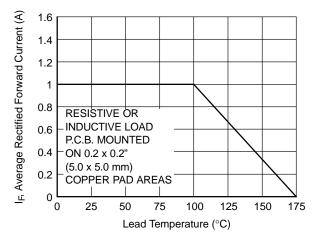


Figure 1. Forward Current Derating Curve

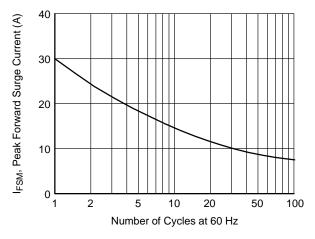


Figure 3. Non-Repetitive Surge Current

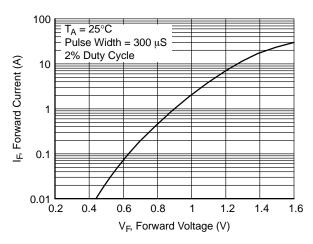


Figure 2. Forward Voltage Characteristics

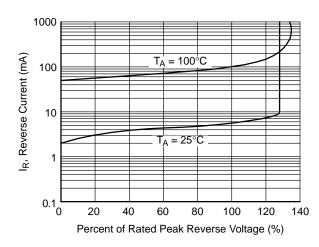


Figure 4. Reverse Current vs. Reverse Voltage

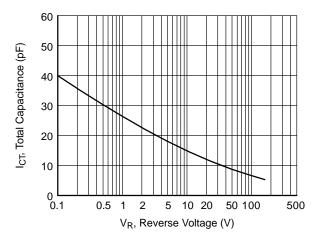
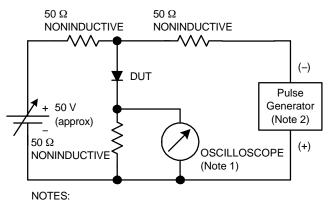


Figure 5. Total Capacitance

EGF1A, EGF1B, EGF1C, EGF1D

REVERSE RECOVERY TIME CHARACTERISTIC AND TEST CIRCUIT DIAGRAM



- 1. Rise time = 7.0 ns max; Input impedance = 1.0 M Ω 22 pF.
- 2. Rise time = 10 ns max; Source impedance = 50 Ω .

Figure 6. Test Circuit Diagram

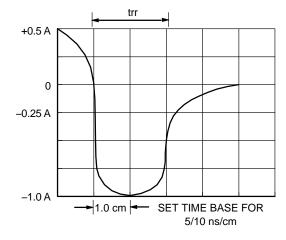
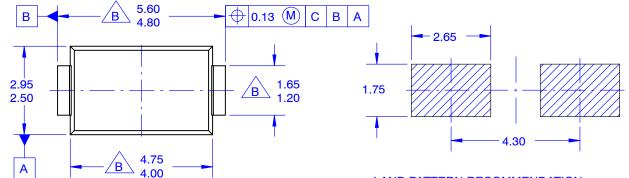


Figure 7. Reverse Recovery Time Characteristic



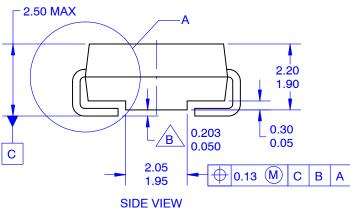
SMA CASE 403AE ISSUE O

DATE 31 AUG 2016



TOP VIEW

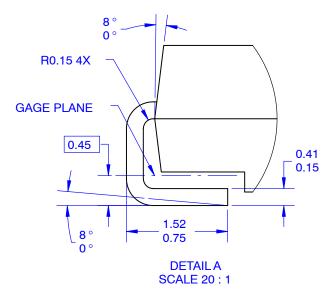
LAND PATTERN RECOMMENDATION



NOTES:

- A. EXCEPT WHERE NOTED, CONFORMS

 \(\times \text{ TO JEDEC DO214 VARIATION AC.} \)
- B DOES NOT COMPLY JEDEC STANDARD VALUE.
- C. ALL DIMENSIONS ARE IN MILLIMETERS.
- D. DIMENSIONS ARE EXCLUSIVE OF BURRS, MOLD FLASH AND TIE BAR PROTRUSIONS.
- E. DIMENSIONS AND TOLERANCE AS PER ASME Y14.5–2009.
- E. LAND PATTERN STD. DIOM5025X231M



DOCUMENT NUMBER: 98AON13440G Printed versions are uncontrolled except when stamped "CONTROLLED COPY" in red.
Fillied versions are uncontrolled except when sampled Controlled Cort in red.

onsemi and ONSeMi are trademarks of Semiconductor Components Industries, LLC dba onsemi or its subsidiaries in the United States and/or other countries. onsemi reserves the right to make changes without further notice to any products herein. onsemi makes no warranty, representation or guarantee regarding the suitability of its products for any particular purpose, nor does onsemi assume any liability arising out of the application or use of any product or circuit, and specifically disclaims any and all liability, including without limitation special, consequential or incidental damages. onsemi does not convey any license under its patent rights nor the rights of others.

onsemi, Onsemi, and other names, marks, and brands are registered and/or common law trademarks of Semiconductor Components Industries, LLC dba "onsemi" or its affiliates and/or subsidiaries in the United States and/or other countries. onsemi owns the rights to a number of patents, trademarks, copyrights, trade secrets, and other intellectual property. A listing of onsemi's product/patent coverage may be accessed at www.onsemi.com/site/pdf/Patent-Marking.pdf. Onsemi reserves the right to make changes at any time to any products or information herein, without notice. The information herein is provided "as-is" and onsemi makes no warranty, representation or guarantee regarding the accuracy of the information, product features, availability, functionality, or suitability of its products for any particular purpose, nor does onsemi assume any liability arising out of the application or use of any product or circuit, and specifically disclaims any and all liability, including without limitation special, consequential or incidental damages. Buyer is responsible for its products and applications using onsemi products, including compliance with all laws, regulations and safety requirements or standards, regardless of any support or applications information provided by onsemi. "Typical" parameters which may be provided in onsemi data sheets and/or specifications can and do vary in different applications and actual performance may vary over time. All operating parameters, including "Typicals" must be validated for each customer application by customer's technical experts. onsemi does not convey any license under any of its intellectual property rights nor the rights of others. onsemi products are not designed, intended, or authorized for use as a critical component in life support systems or any FDA class 3 medical devices with a same or similar classification in a foreign jurisdiction or any devices intended for implantation in the human body. Should Buyer purchase

ADDITIONAL INFORMATION

TECHNICAL PUBLICATIONS:

 $\textbf{Technical Library:} \ \underline{www.onsemi.com/design/resources/technical-documentation}$

onsemi Website: www.onsemi.com

ONLINE SUPPORT: www.onsemi.com/support

For additional information, please contact your local Sales Representative at

www.onsemi.com/support/sales